# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
KAZUHIRO MOCHIZUKI	06/04/2015
HIDEKATSU ONOSE	06/04/2015
NORIFUMI KAMESHIRO	06/01/2015
NATSUKI YOKOYAMA	06/01/2015

### **RECEIVING PARTY DATA**

Name:	HITACHI POWER SEMICONDUCTOR DEVICE, LTD.
Street Address:	2-2, OMIKACHO 5-CHOME
City:	HITACHI-SHI, IBARAKI
State/Country:	JAPAN
Postal Code:	319-1221

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14768173

## **CORRESPONDENCE DATA**

**Fax Number:** (703)610-8686

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 7039039000

**Email:** tpurifoy@milesstockbridge.com, ipdocketing@milesstockbridge.com

Correspondent Name: MITCHELL W. SHAPIRO
Address Line 1: MILES & STOCKBRIDGE P.C.

Address Line 2: 1751 PINNACLE DRIVE, SUITE 1500
Address Line 4: TYSONS CORNER, VIRGINIA 22102

ATTORNEY DOCKET NUMBER: XA-12903/T3381-21700US01

NAME OF SUBMITTER: TYNISHA PURIFOY

SIGNATURE: /Tynisha Purifoy/

DATE SIGNED: 08/31/2015

**Total Attachments: 4** 

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PATENT 503459097 REEL: 036455 FRAME: 0873

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> PATENT REEL: 036455 FRAME: 0874

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI POWER SEMICONDUCTOR DEVICE, LTD., a corporation organized under the laws of Japan,

located at 2-2, Omikacho 5-chome, Hitachi-shi, Ibaraki 319-1221 Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI POWER SEMICONDUCTOR DEVICE, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

#### SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI POWER SEMICONDUCTOR DEVICE, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI POWER SEMICONDUCTOR DEVICE, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTORIO

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)	
1) <u>Kaza</u>	where machizike (Kazuhiro MOCHIZUKI)	June 4, 2015	
2)	(Hidekatsu ONOSE)		
3)	(Norifumi KAMESHIRO)		
4)	(Natsuki YOKOYAMA)		
5)			
6)			
7)			
8)			

Data Olamani

(譲渡証)

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Signed on the date(s) indicated aside our signatures:

Date Signed (署名日)	INVENTOR(S) (発明者フルネームサイン)	
	(Kazuhiro MOCHIZUKI)	1)
June 4, 2015	tide leaten ausse (Hidekatsu ONOSE)	2)
	(Norifumi KAMESHIRO)	3)
	(Natsuki YOKOYAMA)	4)
		5)
		6)
		7)
		8)

PATENT REEL: 036455 FRAME: 0876

(譲渡証)

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INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)	
1)_	(Kazuhiro MOCHIZUKI)		
2)	(Hidekatsu ONOSE)		
3) <u>/</u> /	Norifumi Kameshiro (Norifumi KAMESHIRO)	June 1, 2015	
4)	(Natsuki YOKOYAMA)		
5)			
6)_		<u> </u>	
7)			
8)			

PATENT REEL: 036455 FRAME: 0877

(譲渡証)

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2)	(Hidekatsu ONOSE)	
3)	(Norifumi KAMESHIRO)	
4)	Nortsuki Yokango (Natsuki YOKOYAMA)	June 1, 2015
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RECORDED: 08/31/2015